

ELECTROLYTIC HARD GOLD PLATING SOLUTION SUBSTITUTION
INHIBITOR AND ELECTROLYTIC HARD GOLD PLATING SOLUTION
INCLUDING SAME

ABSTRACT

The present invention provides an electrolytic hard gold plating solution substitution inhibitor characterized by containing at least one compound selected from the group consisting of an imidazole compound having a mercapto group, a triazole compound having a mercapto group, and an aliphatic compound having a sulfonic acid group and a mercapto group, and further provides an electrolytic hard gold plating solution containing said electrolytic hard gold plating solution substitution inhibitor, a gold salt, a soluble cobalt salt and/or a soluble nickel salt, an organic acid conducting salt, and a chelating agent.

[No Suitable Figure]